ABSTRACT

Sheet Removing Apparatus and Method

In an apparatus and method of using an adhesive tape to remove a protecting sheet applied to a semiconductor wafer, a heat-sensitive adhesive tape is thermocompressively bonded by a heat tool to an edge portion of the protecting sheet, after which a cutting blade cuts the adhesive sheet to a prescribed length, and then a tape peeling head grasps the cut adhesive tape and moves in a direction to pull the adhesive tape so as to remove the protecting sheet of the semiconductor wafer, with the removed sheet then being disposed of together with the adhesive tape into a disposal box.

(Fig. 13)